WAFER PROCESSING APPARATUS AND WAFER PROCESSING METHOD

ABSTRACT OF THE DISCLOSURE

There are provide a wafer processing method comprising the steps of securing the entirety of a wafer which is provided, on its right side, with a surface protection tape adhered thereto, to a frame by a dicing tape adhered to the underside of the wafer; irradiating the dicing tape of the wafer with ultraviolet light; and detaching the surface protection tape from the right side of the wafer, wherein the order of the occurrence of an irradiating operation for irradiating the dicing tape with ultraviolet light by the ultraviolet light irradiating portion and a detaching operation for detaching the surface protection tape by the detaching portion is determined based on a relation between the adhesive force of the surface protection tape and the adhesive force of the dicing tape before and after an ultraviolet light irradiating operation carried out by the ultraviolet light irradiating portion, and a wafer processing apparatus for carrying out the method. The apparatus may further comprise a recognizing portion which reads and recognizes a recognition mark provided on at least one of the wafer and the frame. Thus, the order of the occurrence of an ultraviolet light irradiating operation and a surface protection tape detaching operation is determined.

Figure 1